

Amendments to the Claims:

Claims 2, 3, 5, 6, 8, 19, 20, 22, 23 and 25 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Cancelled)
2. (Currently Amended) The assembly system of claim 5 1, wherein the said spheres drop into and pass downwardly through the said through-holes by gravitational force.
3. (Currently Amended) The assembly system of claim 5 1, wherein the said pattern corresponds to a pattern of bond pads on the said substrate.
4. (Cancelled)
5. (Currently Amended) An assembly system for placing a plurality of conductive spheres on a substrate having an upper surface having conductive sites comprising one of recessed sites and level sites with respect to the upper surface, the assembly comprising: a stencil plate with upper and lower surfaces, and a pattern of a plurality of through-holes, The assembly system of claim 1, wherein the diameter of said through-holes of the said pattern are greater than the diameter of the conductive said spheres by up to 1 mm, 1mm the stencil plate configured to place the plurality of conductive spheres in the pattern on a surface of the substrate;
a hopper having side walls formed at a continuous uninterrupted angle extending from an upper opening at the top of the hopper having a first dimension for feeding conductive spheres into a smaller bottom opening having a dimension smaller than the first dimension of the

upper opening extending across the first pattern for dispensing the conductive spheres into said plurality of through-holes extending across the stencil plate, the bottom opening having width in the range of at least two diameters of a conductive sphere to about ten diameters of a conductive sphere, the hopper having a bottom lower surface spaced from an upper surface of the stencil plate a distance in the range of about less than one-third the diameter of a conductive sphere; and

a positioning apparatus for moving the hopper over the pattern relative the stencil plate to place the conductive spheres into the plurality of through-holes onto one of the recessed sites and level sites of the surface of said substrate.

6. (Currently Amended) The assembly system of claim 5 1, wherein the said stencil plate is spaced from the said substrate to restrain the said spheres dropped onto the said substrate within the said pattern.

7. (Cancelled)

8. (Currently Amended) The assembly system of claim 5 1, wherein the said stencil plate is spaced from the said substrate to restrain the said spheres dropped onto depressed bond pads of the said substrate.

9.-17. (Cancelled)

18. (Cancelled)

19. (Currently Amended) The assembly system of claim 22 18, wherein the said spheres drop into and pass downwardly through the said through-holes by gravitational force.

20. (Currently Amended) The assembly system of claim 22 18, wherein the said first pattern corresponds to a pattern of bond pads on the said substrate.

21. (Cancelled)

22. (Currently Amended) An assembly system for positioning a plurality of conductive spheres on a substrate having an upper surface having conductive sites comprising one of recessed sites and level sites with respect to the upper surface, each conductive sphere of the plurality of conductive spheres having a diameter, the assembly comprising:
a stencil plate having an upper surface, having a lower surface, having a pattern of a plurality of through-holes, each through-hole having a diameter, ~~The assembly system of claim 18, wherein the diameters of the said through-holes of the said first pattern are greater than the diameters of the said plurality of spheres by up to 1mm, mm-said stencil plate configured to position the plurality of conductive spheres in the pattern on a proximate surface of the substrate;~~
a hopper having a top opening having a first dimension narrowing through a continuous constant angle from the top opening to a bottom opening with a second dimension extending across the pattern for dispensing the plurality of conductive spheres into the plurality of through-holes of the pattern of the stencil plate, the bottom opening having width in the range of at least two diameters of a conductive sphere to about ten diameters of a conductive sphere, the hopper having a bottom lower surface spaced from an upper surface of the stencil plate a distance in the range of about less than one-half the diameter of a conductive sphere to about less than one-third the diameter of a conductive sphere;
and
a positioning apparatus for moving the hopper over said pattern relative of the stencil plate to position the spheres into the plurality of through-holes onto one of the recessed sites and level sites of the proximate surface of the substrate.

23. (Currently Amended) The assembly system of claim 22 19, wherein the said stencil plate is spaced from the said substrate to restrain the said spheres dropped onto the said substrate within said first pattern.

24. (Cancelled)

25. (Currently Amended) The assembly system of claim 20, wherein the said stencil plate is spaced from the said-substrate to restrain the said spheres dropped onto depressed bond pads of the said substrate.

26.-34. (Cancelled)